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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: (Divisional of U.S. Serial No. 09/322,416 which is
a Continuation of U.S. Serial No. 09/187,617)
Filed: July 3, 2001
Applicant: Austin et al.
Title: **METHOD FOR VACUUM ENCAPSULATION OF
SEMICONDUCTOR CHIP PACKAGES**
Our Ref. No.: NOR-865B

Cincinnati, OH

July 3, 2001

Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to examination of the above-identified application, please
amend the application as follows:

In the Specification:

On page 1, line 1, please insert the following: [The present

application is a divisional of co-pending U.S. Serial No. 09/322,416, filed
and now U.S. Patent No. 6,284,173,
May 28, 1999, which is a continuation of U.S. Serial No. 09/187,617, filed
and now abandoned,
November 6, 1998, the disclosures of which are hereby incorporated herein
by reference in their entirety.--

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